

## **Quarterly Reliability Monitoring Results**

Quarters: Q1/2021 to Q4/2021

Based on structural similarity

| Supplier   |  | User Part Number  |             |           |            |           |  |               |
|--|--|---|-------------|-----------|------------|-----------|--|---------------|
| Nexperia B.V.<br>Name of Laboratory<br>Assembly reliability labs<br>Based on AEC-Q101 Test |  | 2PB1219AR Part Description  |             |           |            |           |  |               |
|  |  |   |             |           |            |           |  | Nexperia DHAM |
|  |  | SMD package   |             |           |            |           |  |               |
|  |  | Test Conditions   | Duration    | # Lots    | # Quantity | # Rejects |  |               |
|  |  |   | TEST        |           |            |           |  |               |
|  | Pre- and Post-Stress                           |   |             |           |            |           |  |               |
| # E1   | Electrical Test                                | Tamb = 25 °C  | N/A         | see below | all parts  | see below |  |               |
|  |  | JESD22-A113<br>Bake Tamb = 125 °C   | 24 hours    |           |            |           |  |               |
|  | PC   | Soak Tamb = 85 °C, RH = 85%   | 168 hours   |           |            |           |  |               |
| # A1   | Preconditioning                                | Reflow soldering  | 3 cycles    | 849       | 61170      | 0         |  |               |
|  |  | MIL-STD-750-1   |             |           |            |           |  |               |
|  | HTRB   | M1039 Method A  |             |           |            |           |  |               |
|  | High Temperature Reverse                       | Tj = Tjmax, Vr = 100% of max. datasheet   |             |           |            |           |  |               |
| # B1   | Bias   | reverse voltage   | 1000 hours  | 202       | 16160      | 0         |  |               |
|  | тс   | JESD22-A104   |             |           |            |           |  |               |
| # A4   | Temperature Cycling                            | -65 °C to Tjmax, not to exceed 150°C  | 1000 cycles | 171       | 13680      | 0         |  |               |
|  |  | JESD22-A102   |             |           |            |           |  |               |
|  | AC   | Tamb = 121 °C, RH = 100 %   |             |           |            |           |  |               |
| # A3 alt   | Autoclave                                      | Pressure = 205 kPa (29.7 psia)  | 96 hours    | 173       | 13840      | 0         |  |               |
|  |  |   |             |           |            |           |  |               |
|  | H3TRB  | JESD22-A101   |             |           |            |           |  |               |
| " • <b>&gt;</b> - !!   | High Humidity High<br>Temperature Reverse Bias | Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage <sup>[1]</sup>       | 1000        | 4 7 9     | 10010      |           |  |               |
| # A2 alt   | Temperature Reverse Blas                       |   | 1000 hours  | 173       | 13840      | 0         |  |               |
|  | IOL  | MIL-STD-750 Method 1037<br>ton = toff, devices powered to insure $\Delta T_j$ = |             |           |            |           |  |               |
| # A5   | Intermittent Operating Life                    |   | 1000 hours  | 197       | 15760      | 0         |  |               |
| # A5   | inconnection operating Life                    |   | 1000 10015  | 197       | 13/00      | 0         |  |               |
|  | RSH  | JESD22-A111   |             |           |            |           |  |               |
| # C8   | Resistance to Solder Heat                      |   | 10 s        | 135       | 4050       | 0         |  |               |
|  | SD   |   |             |           |            | -         |  |               |
| # C10  | Solderability                                  | J-STD-002   |             | 342       | 3420       | 0         |  |               |

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab        | Technology                         | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|------------------|------------------------------------|----------|---------|--------------------|------------|
| Nexperia<br>DHAM | Small Signal Bipolar<br>Transistor | 16160    | 0       | 0.26               | 3.81E+09   |

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